



Product Change Notification

Change Notification #: 118608-01
Change Title: Intel® RAID Module RMSP3AD160F
Intel® RAID Module RMSP3CD080F
PCN 118608-01, Product Discontinuance,
End of life
[Reason for Revision: Change to Public Access in QDMS](#)
Date of Publication: October 28, 2021

Key Characteristics of the Change:

Product Discontinuance

Forecasted Key Milestones:

Product Discontinuance Program Support Begins	October 22, 2021
Last Product Discontinuance Order Date	March 15, 2022
Orders are Non-Cancelable and Non-Returnable After	February 15, 2022
Last Product Discontinuance Shipment Date	April 28, 2023

Description of Change to the Customer:

[Reason for Revision: Change to Public Access in QDMS](#)

The Intel SKUs listed in the products affected table will End of life

Customer Impact of Change and Recommended Action:

Determine your remaining demand for this product and order accordingly.

Intel reserves the right to extend the Last Product Discontinuance Shipment Date based on manufacturing capabilities and supply availability.

The recommended replacement SKUs are noted within the affected products table within this PCN notice but Intel recommends to contact your local Intel Field Sales Representative as form factor may be different and additional options will be available at a later date.

Please contact your local Intel Field Sales Representative if you have any further questions about the product transition or End of Life process.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	Affected MM#	Recommended replacement Product Code	Recommended replacement MM#
Intel® RAID Module RMSP3CD080F, 5 Pack	RMSP3CD080F	954489	RS3P4TF160F	999TJ4
Intel® RAID Module RMSP3AD160F, 5 Pack	RMSP3AD160F	954552	RS3P4TF160F	999TJ4

PCN Revision History:

Date of Revision:

October 22, 2021

October 28, 2021

Revision Number:

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Reason:

Originally Published PCN

Change to Public Access in QDMS



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

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